

PART INFORMATION		
Mfg Item Number	MC17XSF500EK	
Mfg Item Name	ESOIC 32 7.5*11*2.3 P.65	
SUPPLIER		
Company Name	Freescale Semiconductor Inc	
Company Unique ID	14-141-7928	
Response Date	2017-02-07	
Response Document ID	00A0K00184D006A1.10	
Contact Name	Freescale Semiconductor Inc	
Contact Title	Product Technical Support	
Contact Phone	1-800-521-6274	
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Authorized Representative	Daniel Binyon	
Representative Title	EPP Customer Response	
Representative Phone	512-895-3406	
Representative Email	eppanlst@freescale.com	
URL for Additional Information	www.freescale.com	
DECLARATION		
EU RoHS	Yes	
Pb Free	Yes	
HalogenFree	Yes	
Plating Indicator	e3	
EU RoHS Exemption(s)		
MANUFACTURING		
Mfg Item Number	MC17XSF500EK	
Mfg Item Name	ESOIC 32 7.5*11*2.3 P.65	
Version	ALL	
Weight	0.487000	
UoM	g	
Unit Volume	EACH	
J-STD-020 MSL Rating	3	
Peak Processing Temperature	260 C	
Max Time at Peak Temperature	40 seconds	
Number of Processing Cycles	3	

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight  6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Die Encapsulant	0.3327						g					
Die Encapsulant		Plastics/polymers	4,4'-dihydroxy-3,3',5,5'-tetramethylbiphenyl diglycidyl ether	85954-11-6		0.00514354	g	15460	1.546		10561	1.0561
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.00060518	g	1819	0.1819		1242	0.1242
Die Encapsulant		Metals	Magnesium dihydroxide	1309-42-8		0.01193395	g	35670	3.567		24505	2.4505
Die Encapsulant		Solvents, additives, and other materials	Proprietary Material-Other organic phosphorous compounds	-		0.00026383	g	793	0.0793		541	0.0541
Die Encapsulant		Plastics/polymers	1,3,5-Triazine-2,4,6-triamine, polymer with formaldehyde and phenol	25917-04-8		0.00105166	g	3161	0.3161		2159	0.2159
Die Encapsulant		Plastics/polymers	Phenol p-xylylene dimethyl ether copolymer	26834-02-6		0.01209265	g	36347	3.6347		24830	2.483
Die Encapsulant		Glass	Silica, vitreous	60676-86-0		0.28406127	g	853806	85.3806		583301	58.3301
Die Encapsulant		Metals	Zinc Hydroxide	20427-58-1		0.00554677	g	16672	1.6672		11389	1.1389
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Non-halogenated Epoxy resins	-		0.01200115	g	36072	3.6072		24643	2.4643
Bonding Wire, Aluminum	0.0127						g					
Bonding Wire, Aluminum		Metals	Aluminum, metal	7429-90-5		0.0127	g	1000000	100		26078	2.6078
Lead Frame Plating	0.0162						g					
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00000324	g	200	0.02		6	0.0006
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.01619676	g	998800	99.98		33258	3.3258
Bonding Wire	0.0014						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0014	g	1000000	100		2874	0.2874
Non-Conductive Epoxy/Adhesive	0.0016						g					
Non-Conductive Epoxy/Adhesive		Metals	Aluminum Oxides (Al2O3)	1344-29-1		0.0010176	g	636000	63.6		2089	0.2089
Non-Conductive Epoxy/Adhesive		Glasses	Boric acid	10043-35-3		0	g	0	0		0	0
Non-Conductive Epoxy/Adhesive		Metals	Boron oxide	1303-86-2		0	g	0	0		0	0
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00004	g	25000	2.5		82	0.0082
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Other Bismaleimides	-		0.00008096	g	50600	5.06		166	0.0166
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Toluene	108-88-3		0	g	0	0		0	0
Non-Conductive Epoxy/Adhesive		Metals	Copper phthalocyanine	147-14-6		0.00000064	g	400	0.04		1	0.0001
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Boron nitride	10043-11-5		0.0002208	g	138000	13.8		453	0.0453
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Triethylamine	121-44-8		0	g	0	0		0	0
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Isobornyl acrylate	5888-33-5		0.00024	g	150000	15		492	0.0492
Bonding Agent	0.0058						g					
Bonding Agent		Metals	Silver, metal	7440-22-4		0.004408	g	760000	76		9051	0.9051
Bonding Agent		Plastics/polymers	Other Non-halogenated Epoxy resins	-		0.00026223	g	48660	4.866		579	0.0579
Bonding Agent		Metals	Dibutyltin disulfate	77-59-7		0.00000197	g	340	0.034		4	0.0004
Bonding Agent		Solvents, additives, and other materials	Alkanes, C14-16	90622-46-1		0.000812	g	140000	14		1667	0.1667
Bonding Agent		Plastics/polymers	1,3-Benzenedicarboxylic acid, polymer with 1,4-benzenedicarboxylic acid, 1,4-butanediol and hexanedi	86027-02-9		0.0002958	g	51000	5.1		607	0.0607
Silicon Semiconductor Die	0.0019						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000038	g	20000	2		78	0.0078
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.001862	g	980000	98		3823	0.3823
Copper Lead Frame	0.1128						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.10873412	g	963955	96.3955		223273	22.3273
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00009306	g	825	0.0825		191	0.0191
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.0026508	g	23500	2.35		5443	0.5443
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1		0.00001918	g	170	0.017		39	0.0039
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.001128	g	10000	1		2316	0.2316
Copper Lead Frame		Metals	Tin, metal	7440-31-5		0.00003384	g	300	0.03		69	0.0069
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.000141	g	1250	0.125		289	0.0289
Silicon Semiconductor Die	0.0019						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000038	g	20000	2		78	0.0078
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.001862	g	980000	98		3823	0.3823

LINKS	
MCD LINK	
NXP website	<a href="http://www.nxp.com">http://www.nxp.com</a>
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf</a>
China RoHS	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY</a>
REACH signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf</a>
ELV signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf</a>
Conflict Minerals statement	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf</a>
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX</a>
FAQ	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ</a>
Technical Service Request	<a href="http://www.nxp.com/support/sales-and-support:SUPPORTHOME">http://www.nxp.com/support/sales-and-support:SUPPORTHOME</a>
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	<a href="http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf">http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf</a>

IPC1752 XML LINKS

[http://www.freescale.com/mcds/MC17XSF500EK\\_IPC1752\\_v11.xml](http://www.freescale.com/mcds/MC17XSF500EK_IPC1752_v11.xml)

[http://www.freescale.com/mcds/MC17XSF500EK\\_IPC1752A.xml](http://www.freescale.com/mcds/MC17XSF500EK_IPC1752A.xml)